

TDFM2A-5775T-10A-02

Rev. A

Part Number/Tape & Reel information

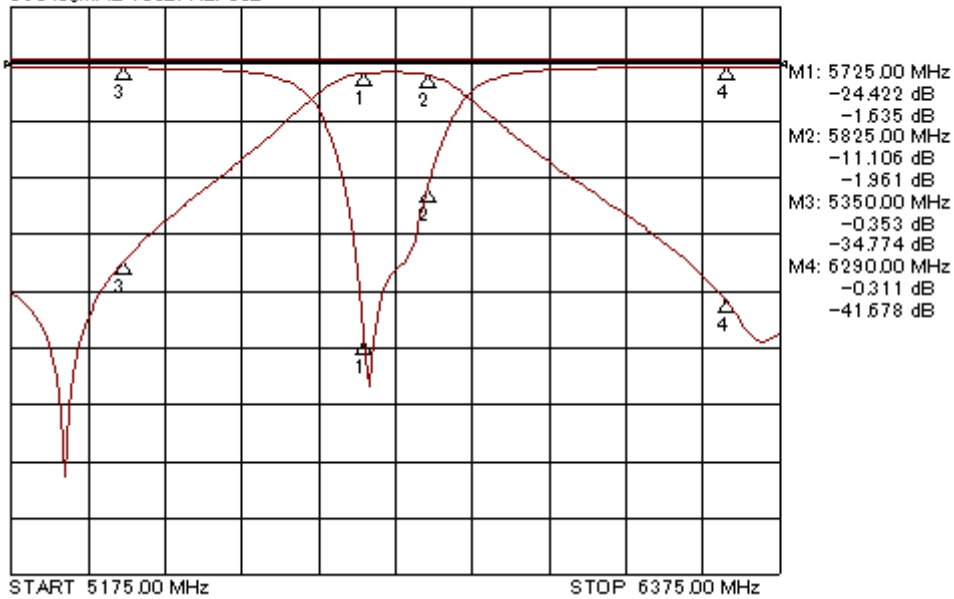
Part Number	Packaging	MOQ
TDFM2A-5775T-10A-02P	330 mm dia. reel	2000 pcs/reel

Specifications -40 to +75°C

Parameter	IN to OUT
Center Frequency	F0 : 5775 MHz
Band Width (BW)	F0 +/- 50 MHz
Insertion Loss	3.4 dB max.
Ripple at BW	1.5 dB max.
V.S.W.R. at BW	2.8 max.
Input Power	1.0 W max.
Attenuation	5350MHz 25dB min. 6290MHz 25dB min.
Characteristic Impedance	50 Ohms

Frequency Response

S11 logMAG 5dB/REF0dB
S21 logMAG 10dB/REF0dB
S32 logMAG 10dB/REF0dB

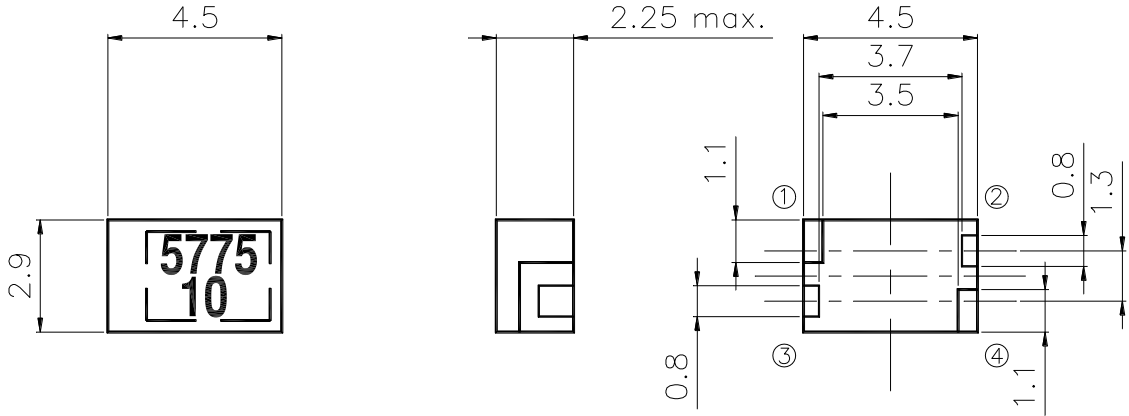


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*Note: All the technical data and information contained herein are subject to change without advanced notice.

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Dimensions and Marking

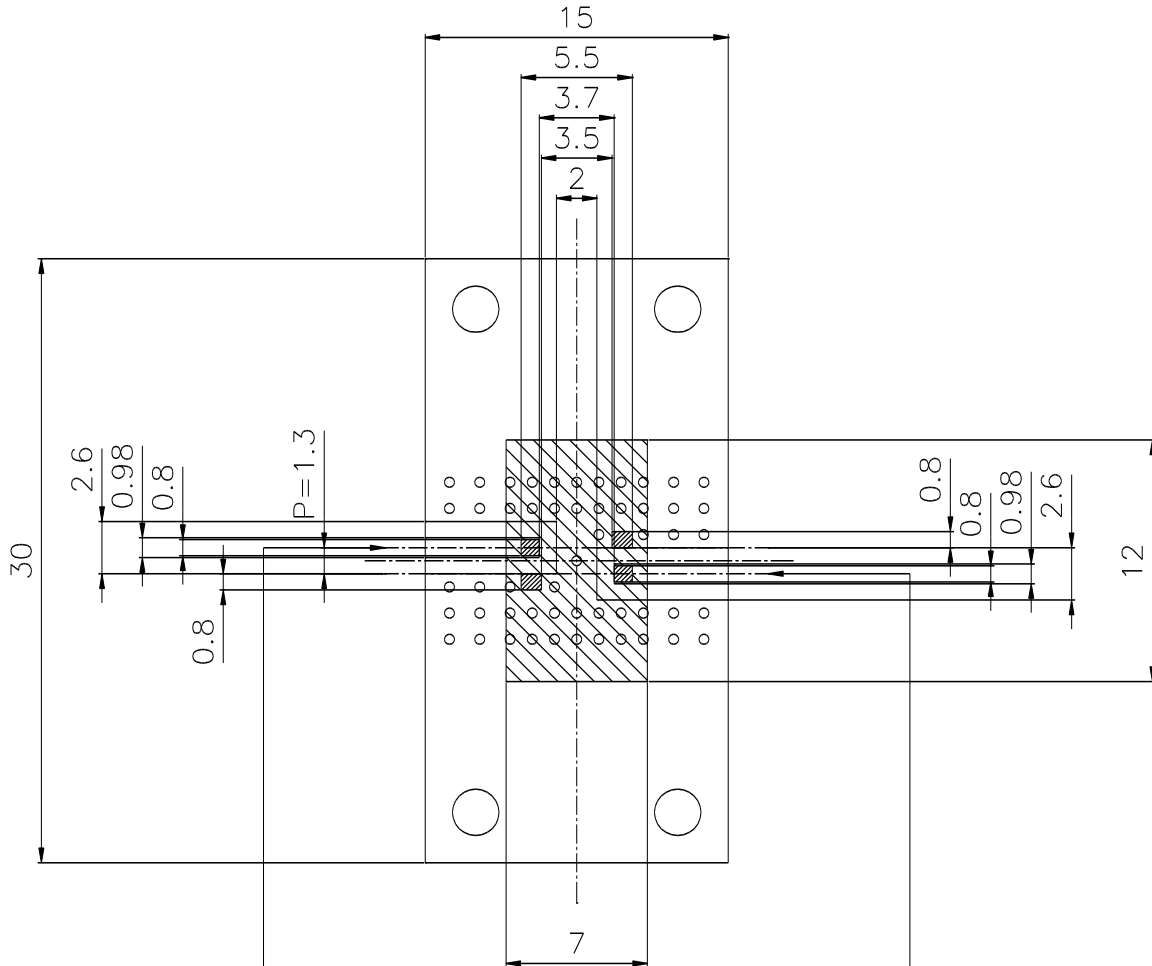


Tolerance: ± 0.3
Unit : mm

①	GND	②	IN
③	OUT	④	GND

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Recommend Land Pattern (reference)



Impedance of signal lines should be 50Ω including land pattern.

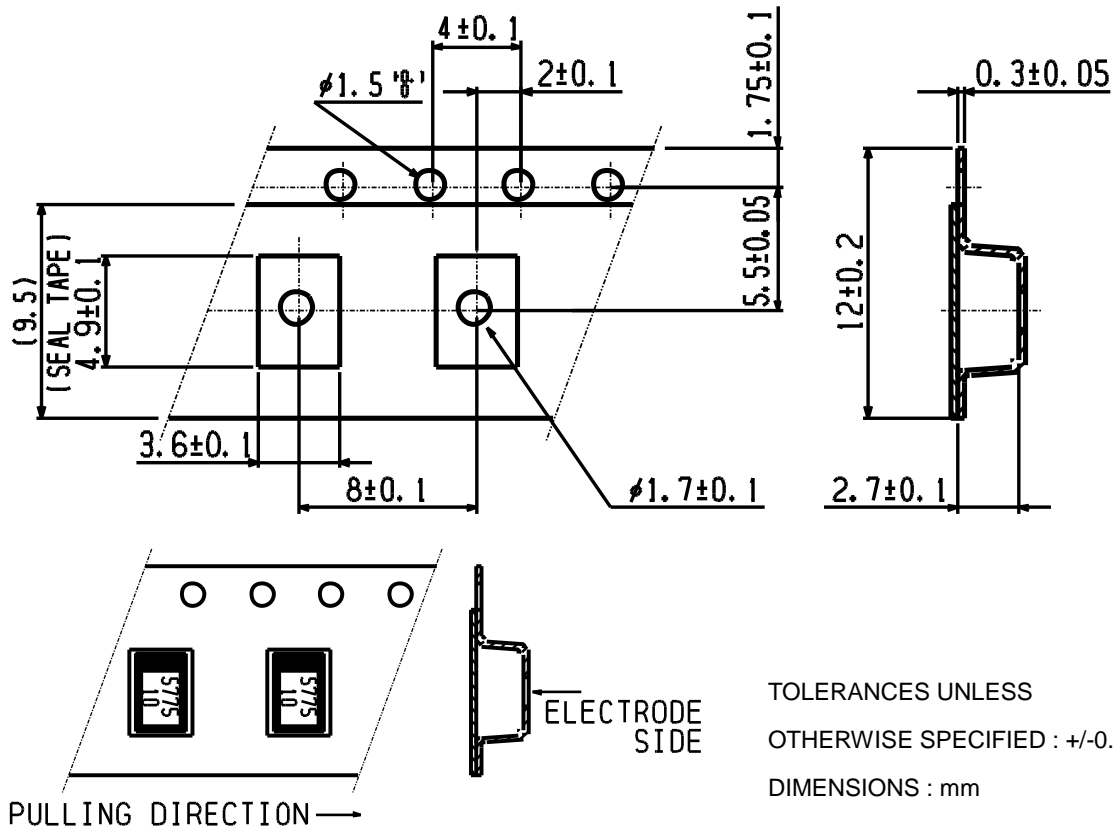
-  Soldering Parts
-  Solder Resist

Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the BT resin board (t = 0.4, dielectric constant = 3.6, copper plating on both surfaces).

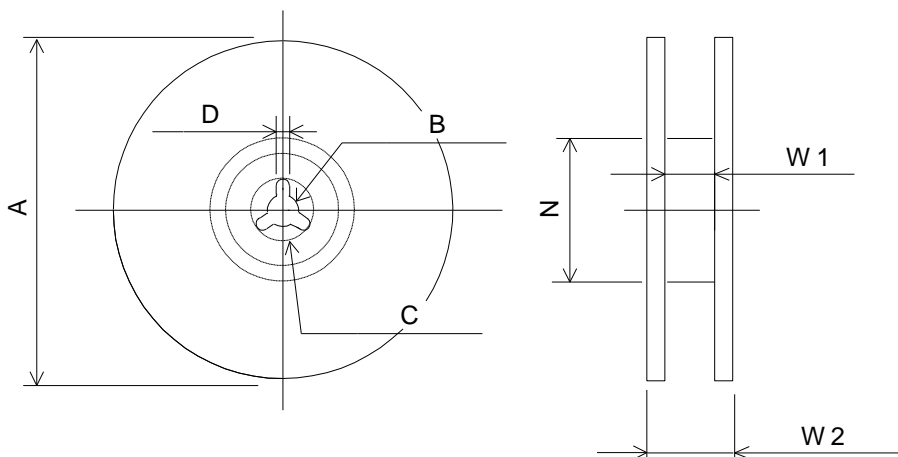
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Dimensions of Carrier Tape



Dimensions of Reel



Murata Part Number	A+/-2.0	B+/-0.5	C+/-1.0	D+/-0.5	N (min.)	W1+/-0.5	W2+/-1.0
TDFM2A-5775T-10A-02P	φ 330	φ 13	φ 21	2	φ 80	13.5	17.5

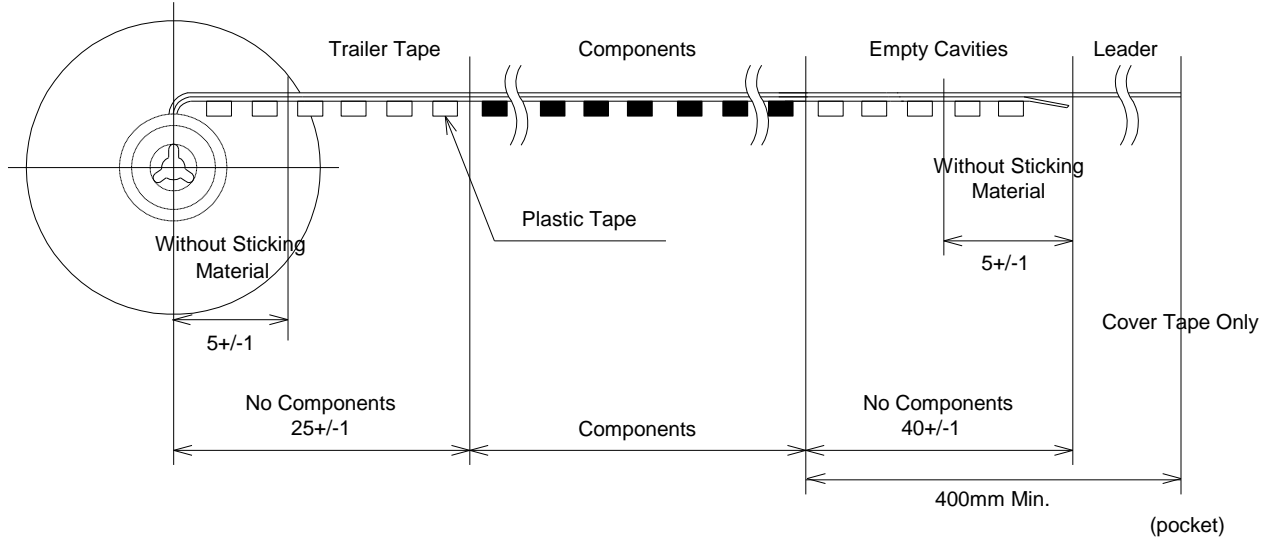
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Taping Condition

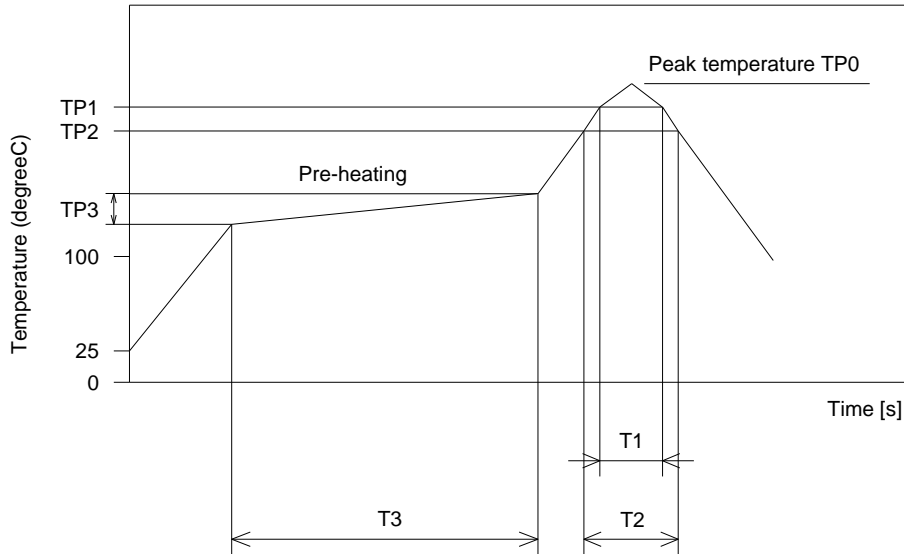


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Reflow Soldering Standard Conditions



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

		TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)	T3 (s)
Reflow standard condition	Sn-40Pb solder	235+/-5	230	10 max.	200	45 to 55	70 to 130	70 to 130
	Sn-3Ag-0.5Cu solder	255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120
Test condition of reflow heat resistance		255+/-5	250	10 max.	220	20 to 40	150 to 190	60 to 120

Reflow soldering is available 2 times for above test condition of reflow heat resistance.